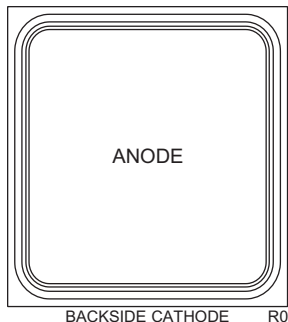


CPD81X-CZSH5-40

Schottky Rectifier Die

5.0 Amp, 40 Volt

The CPD81X-CZSH5-40 is a silicon Schottky rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

Die Size	72.4 x 72.4 MILS
Die Thickness	5.9 MILS
Anode Bonding Pad Size	64 x 64 MILS
Top Side Metalization	Al – 30,000Å
Back Side Metalization	Au – 9,000Å
Scribe Alley Width	2.36 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	3,137

MAXIMUM RATINGS: ($T_A=25^{\circ}\text{C}$)

Peak Repetitive Reverse Voltage
DC Blocking Voltage
RMS Reverse Voltage
Average Forward Current ($T_A=75^{\circ}\text{C}$)
Peak Forward Surge Current, $t_p=8.3\text{ms}$
Operating and Storage Junction Temperature

SYMBOL

V_{RRM}
V_R
$V_{R(RMS)}$
I_O
I_{FSM}
T_J, T_{stg}

40
40
28
5.0
125
-65 to +150

UNITS

V
V
V
A
A
$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^{\circ}\text{C}$)

SYMBOL	TEST CONDITIONS
I_R	$V_R=40\text{V}$
V_F	$I_F=5.0\text{A}$
C_J	$V_R=0, f=1.0\text{MHz}$

MIN

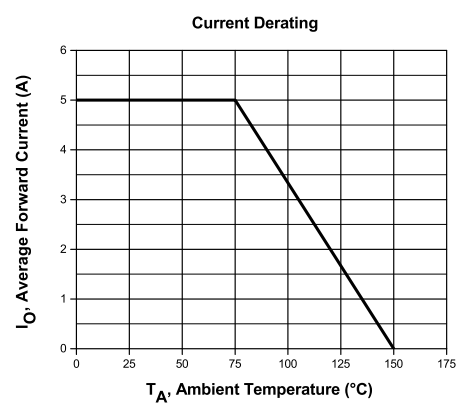
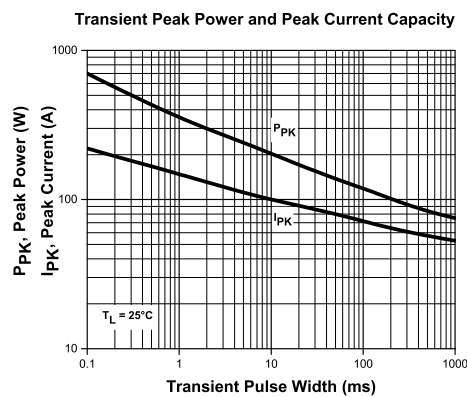
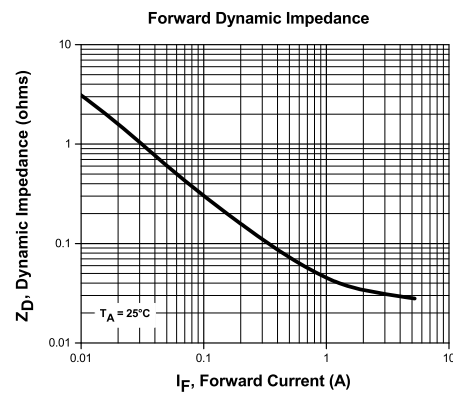
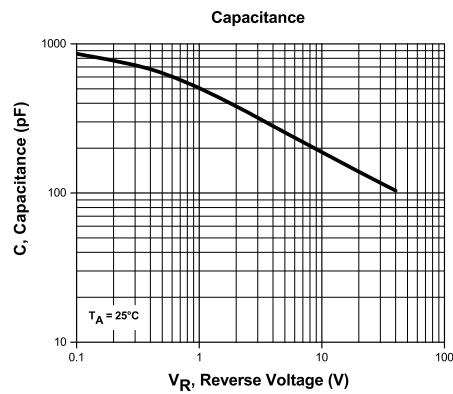
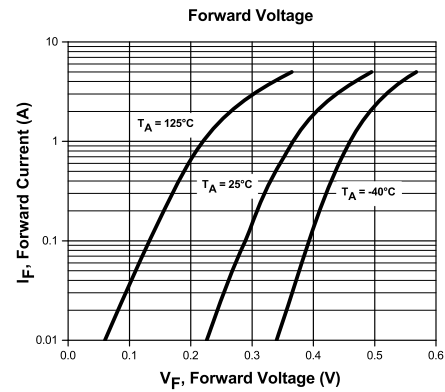
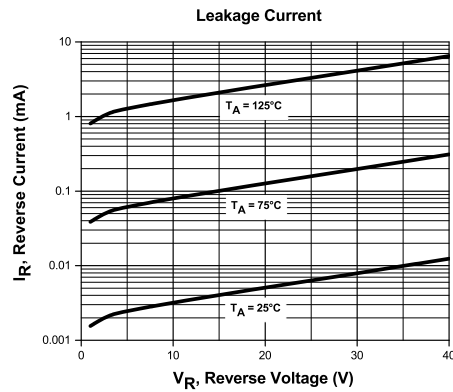
MAX

UNITS

3.0	mA
0.55	V
1500	pF

CPD81X-CZSH5-40

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centralemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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